

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

26. (Withdrawn) A method comprising:

forming a protective coating of polypara-xylylene on an exposed surface of an integrated power device, including forming the protective coating on a conductive termination connected to a semiconductor in the power device; and

cutting a window in the protective coating using a laser to expose the termination.

27. (Withdrawn) A method comprising:

forming a protective coating on an expose surface of an electronic device, including forming the protective coating on a conductive termination connected to a circuit element in the electronic device;

making a window in the protective coating to expose the termination;

applying solder to the portion of the conductive termination exposed by the window in the protective coating; and

encapsulating the electronic device in a potting material.

28. (Withdrawn) A method for use with an electronic device having a conductive termination pad and an electronic component connected to the pad, the method comprising:

applying a protective coating to surfaces of the termination pad and the electronic component;

cutting a window in the protective coating to expose the termination pad; and

flowing solder into the window to make electrical connection between the solder pad and a circuit.

29. (Cancelled)

30. (Currently Amended) An apparatus comprising:
an electronic device having a an outer surface and a conductive termination on the surface;
a protective, conformal coating on the outer surface of the electronic device; and
a window formed in the protective coating to expose a portion of the conductive termination[;], wherein the exposed portion of the conductive termination is recessed in the window of the conformal coating.

31. (Previously Added) The apparatus of claim 30 wherein the coating comprises a uniform thickness.

32. (Previously Added) The apparatus of claim 30 wherein the coating conforms to the geometric configuration of the electronic device.

33. (Previously Added) The apparatus of claim 30 wherein the coating comprises a polymer.

34. (Previously Added) The apparatus of claim 33 wherein the polymer comprises poly-para-xylylene.

35. (Previously Added) The apparatus of claim 30 wherein the electronic device comprises an integrated power device (IPD).

36. (Previously Added) The apparatus of claim 30 wherein the electronic device further comprises a semiconductor.

37. (Previously Added) The apparatus of claim 30 wherein the electronic device further comprises power semiconductor.

38. (Previously Added) The apparatus of claim 30 wherein the window restricts the region of the termination to which solder can adhere, the exposed portion defining a location for a solder bond.

39. (Currently Amended) The apparatus of claim 30 wherein the electronic device comprises a plurality of conductive terminations and the conductive protective coating comprises a plurality of windows that each expose a portion of the conductive termination, wherein the exposed portion of each termination is recessed within the window of the protective coating. --